What is claimed is:

1. An antenna interface circuit to provide an interface between a packaged microelectronic device and an antenna, comprising:

at least one of the following on one or more substrates: metallization forming a power amplifier impedance transformer, metallization forming a low noise amplifier input matching circuit, and metallization forming a duplexer to couple an external transmitter and an external receiver to a common antenna; and

at least one electrical terminal to couple said antenna interface circuit to a microelectronic device package.

2. The antenna interface circuit of claim 1, wherein:

said at least one electrical terminal is for direct connection to one or more corresponding terminals on a side of the microelectronic device package that has a microelectronic die mounted thereto.

3. The antenna interface circuit of claim 1, further comprising:

at least one electrical terminal to couple said antenna interface circuit to an external antenna.

4. The antenna interface circuit of claim 1, further comprising:

metallization forming an integrated antenna.

5. The antenna interface circuit of claim 1, wherein:

said antenna interface circuit includes multiple metallization layers.

6. The antenna interface circuit of claim 5, comprising:

metallization forming a power amplifier impedance transformer on one metallization layer and metallization forming a low noise amplifier input matching circuit on another, different metallization layer.

7. The antenna interface circuit of claim 5, wherein:
at least one of said multiple metallization layers includes a ground plane.

8. The antenna interface circuit of claim 1, wherein:
said antenna interface circuit is flexible.

9. The antenna interface circuit of claim 1, wherein:
said at least one electrical terminal includes a ball grid array (BGA).

10. The antenna interface circuit of claim 1, further comprising:
metallization forming at least one radio frequency choke to couple a transistor within the packaged microelectronic device to a power supply.

11. An antenna interface circuit to provide an interface between a packaged microelectronic device and an antenna, comprising:
first metallization forming a power amplifier impedance transformer, second metallization forming a low noise amplifier input matching circuit, and third metallization forming a duplexer to couple an external transmitter and an external receiver to a common antenna, said first metallization being connected to said third metallization and said second metallization being connected to said third metallization, wherein said first, second, and third metallizations are on one or more substrates;
at least one electrical terminal to couple said first metallization to a microelectronic device; and
at least one electrical terminal to couple said second metallization to the microelectronic device.

12. The antenna interface circuit of claim 11, further comprising:
at least one electrical terminal to connect said third metallization to an external antenna.

13. The antenna interface circuit of claim 11, further comprising:

fourth metallization, connected to said third metallization, forming an integrated antenna.

14. The antenna interface circuit of claim 11, wherein:

said antenna interface circuit includes multiple metallization layers, wherein said first metallization is located on a first metallization layer and said second metallization is located on a second, different metallization layer.

15. The antenna interface circuit of claim 14, further comprising:

a ground plane located on a third metallization layer, said third metallization layer being located between said first metallization layer and said second metallization layer.

16. The antenna interface circuit of claim 11, wherein:

said antenna interface circuit is flexible.

17. A system comprising:

a microelectronic device including: (a) a package having an upper side and a lower side, and (b) at least one microelectronic die having wireless circuitry therein mounted on said upper side of said package, wherein said lower side of said package includes a plurality of terminals to couple said package to a circuit board and said upper side of said package includes at least one terminal to provide communication with an external antenna; and

an antenna interface circuit to provide an interface between said microelectronic device and an antenna, said antenna interface circuit having at least one terminal that is connected to said at least one terminal on said upper side of said package.

18. The system of claim 17, wherein:

said antenna interface circuit includes power amplifier impedance transformer circuitry.

19. The system of claim 17, wherein:

said antenna interface circuit includes low noise amplifier input matching circuitry.

20. The system of claim 17, wherein:

said antenna interface circuit includes duplexer circuitry to allow a wireless transmitter and a wireless receiver within said microelectronic device to share a common antenna.

21. The system of claim 17, wherein:

said antenna interface circuit includes power amplifier impedance transformer circuitry, low noise amplifier input matching circuitry, and duplexer circuitry to allow a wireless transmitter and a wireless receiver within said microelectronic device to share a common antenna.

22. The system of claim 17, wherein:

said antenna interface circuit includes multiple metallization layers.

23. The system of claim 22, wherein:

said antenna interface circuit includes power amplifier impedance transformer circuitry on a first metallization layer and low noise amplifier input matching circuitry on a second metallization layer, wherein said second metallization layer is different from said first metallization layer.

24. The system of claim 17, wherein:

said antenna interface circuit includes at least one antenna integrated therein.

25. The system of claim 17, wherein:

said antenna interface circuit is coupled to an external antenna.

26. The system of claim 17, wherein:

said at least one microelectronic die is mounted on said upper side of said package using flip chip techniques.

27. The system of claim 17, wherein:

said plurality of terminals on said lower side of said package includes at least one of: a ball grid array (BGA), a pin grid array (PGA), and a land grid array (LGA).

28. The system of claim 17, wherein:

said antenna interface circuit is flexible.

29. A system comprising:

a patch antenna; and

an antenna interface circuit to provide an interface between a microelectronic device and said patch antenna, said antenna interface circuit including:

first metallization forming a power amplifier impedance transformer, second metallization forming a low noise amplifier input matching circuit, and third metallization forming a duplexer to couple an external transmitter and an external receiver to said patch antenna, said first metallization being connected to said third metallization and said second metallization being connected to said third metallization, wherein said first, second, and third metallizations are on one or more substrates;

at least one electrical terminal to couple said first metallization to a microelectronic device; and

at least one electrical terminal to couple said second metallization to the microelectronic device.

30. The system of claim 29, wherein:

said antenna interface circuit includes multiple metallization layers, wherein said first metallization is located on a first metallization layer and said second metallization is located on a second, different metallization layer.

31. The system of claim 30, further comprising:

a ground plane located on a third metallization layer of said antenna interface circuit, said third metallization layer being located between said first metallization layer and said second metallization layer.

32. The system of claim 29, wherein:

said antenna interface circuit is flexible.

33. A microelectronic device comprising:

a package having an upper side and a lower side; and

at least one microelectronic die having wireless circuitry therein mounted to said upper side of said package;

wherein said lower side of said package includes a plurality of terminals to couple said package to a circuit board and said upper side of said package includes at least one terminal to couple said microelectronic device to an external antenna.

34. The microelectronic device of claim 33, wherein:

said at least one microelectronic die includes a die having both digital processing circuitry and wireless transceiver circuitry located therein.

35. The microelectronic device of claim 33, wherein:

said at least one microelectronic die is mounted to said upper side of said package using flip chip techniques.

36. The microelectronic device of claim 33, wherein:

said package includes power amplifier impedance transformer circuitry.

37. The microelectronic device of claim 36, wherein:

said package includes low noise amplifier input matching circuitry.

38. The microelectronic device of claim 37, wherein:

said package includes duplexer circuitry to allow a wireless transmitter and a wireless receiver within said microelectronic device to share a common external antenna.

39. The microelectronic device of claim 33, wherein:

said at least one terminal on said upper side of said package includes at least one terminal to connect said microelectronic device to an external power amplifier impedance transformer.

40. The microelectronic device of claim 39, wherein:

said at least one terminal on said upper side of said package includes at least one terminal to connect said microelectronic device to an external low noise amplifier input matching circuit.

41. A microelectronic device comprising:

a package having an upper side and a lower side;

at least one microelectronic die having wireless circuitry therein mounted to said upper side of said package, wherein said lower side of said package includes a plurality of terminals to couple said package to a circuit board and said upper side of said package includes at least one terminal to couple said microelectronic device to an external antenna; and

an antenna circuit coupled to said at least one terminal on said upper side of said package, said antenna circuit including at least one microstrip antenna element.

42. The microelectronic device of claim 41, wherein:

said at least one microstrip antenna element includes a patch element.

43. The microelectronic device of claim 41, wherein:

said antenna circuit is flexible.